

2.5V - 5.5V Input / 1A Output / 0.8V - 5.5V Output

DESCRIPTION

The VDMM 171010502 Magl³C power module provides a fully integrated DC-DC power supply including the switching regulator IC with integrated MOSFETs, controller, compensation and shielded inductor in one package.

The 171010502 offers high efficiency and delivers up to 1A of output current. It operates with an input voltage from 2.5V to 5.5V and is designed for a small solution size.

The selectable mode pin allows for the choice between high efficiency and low output voltage ripple at light load.

The 171010502 is available in an LGA-6EP package $(3.2 \times 2.5 \times 1.55 \text{mm})$.

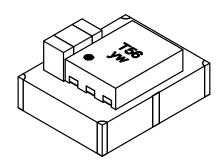
This power module has integrated protection circuitry that guards against thermal overstress with thermal shutdown and protects against electrical damage using overcurrent, short-circuit and undervoltage protections.

TYPICAL APPLICATIONS

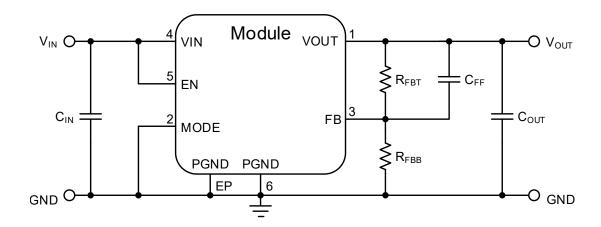
- Point of load power supply for low power systems
- Replacement of linear regulators
- DSP and FPGA power supply auxiliary voltages
- Portable instruments
- Battery powered equipment

FEATURES

- Peak efficiency up to 96%
- Input voltage range: 2.5V to 5.5V
- Typical quiescent current: 23.5μA
- Output voltage range: 0.8V to 5.5V
- Current capability up to 1A
- Constant on-time control
- Synchronous operation
- Fixed switching frequency: 4MHz
- Selectable modes of operation
- Embedded soft-start
- Undervoltage lockout (UVLO)
- Cycle-by-cycle current limit
- Short-circuit protection
- Thermal shutdown
- Ambient temp. range: -40°C to 85°C
- Junction temp. range: -40°C to 125°C
- RoHS und REACH compliant
- Complies with EN55032 class B radiated emissions standard



TYPICAL CIRCUIT DIAGRAM



Magl³C Power Module

WPME-VDMM - Variable Step Down MicroModule



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1 PINOUT

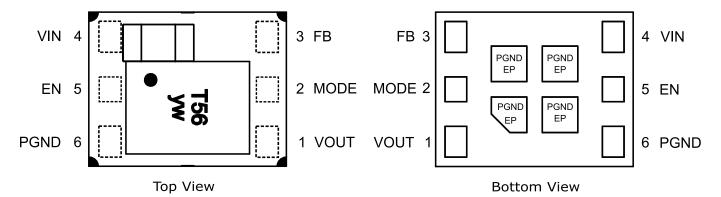


Figure 1: Pinout.

Table 1: Pin description.

SYMBOL	NUMBER	TYPE	DESCRIPTION
VOUT	1	Power	Output voltage. Place output capacitors as close as possible to VOUT and PGND. For thermal performance, use a copper plane at this pin.
MODE 2 Input during light load conditions. Pulling this pin low		Mode selection pin. Pulling this pin high will prevent PFM from engaging during light load conditions. Pulling this pin low will enable PFM operation during light load conditions. This pin must not be left floating.	
FB	3	Input	Feedback pin. This pin must be connected to the external resistor divider (between VOUT and PGND) to adjust the output voltage.
VIN	VIN 4 Power		Input voltage. Place the input capacitor as close as possible to VIN and PGND.
EN	5	Input	Enable pin. Pulling this pin high enables the device, while pulling this pin low shuts down the device. This pin must not be left floating.
PGND	6	Power	Power ground pin. This pin must be connected to the ground plane and to the thermal pad.
PGND	EP	Exposed Pad	Exposed pad. The exposed pad is internally electrically connected to PGND. It is recommended to connect it to the ground plane for optimal device heat dissipation.

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2 ORDERING INFORMATION

Table 2: Ordering information.

ORDER CODE	SPECIFICATIONS	PACKAGE	PACKAGING UNIT
171010502	1A / 0.8V-5.5V Vout version	LGA-6EP	7" Reel (2000 pieces)
178010502	1A / 0.8V-5.5V Vout version	Eval Board	Box with 1 piece

3 SALES INFORMATION

Table 3: Sales information.

SALES CONTACT Würth Elektronik eiSos GmbH & Co. KG EMC and Inductive Solutions Max-Eyth-Str. 1 74638 Waldenburg Germany Tel. +49 (0) 7942 945 0

www.we-online.com/powermodules Technical support: powermodules@we-online.com



4 ABSOLUTE MAXIMUM RATINGS

Caution:

Exceeding the listed absolute maximum ratings may affect the device negatively and may cause permanent damage.

Table 4: Absolute maximum ratings.

SYMBOL	PARAMETER	LIN	UNIT	
J TWIDOL	PARAMETER	MIN ⁽¹⁾	MAX ⁽¹⁾	ONT
VIN	Input pin voltage	-0.3	6	V
VOUT	Output pin voltage	-0.3	V _{IN} +0.3	V
FB	Feedback pin voltage	-0.3	V _{IN} +0.3	V
EN	Enable pin voltage	-0.3	V _{IN} +0.3	V
MODE	Mode pin voltage	-0.3	V _{IN} +0.3	V
$T_{storage}$	Assembled, non-operating storage temperature	-40	125	°C
V_{esd}	ESD Voltage (HBM), All pins vs. PGND (C=100pF, R=1.5kΩ) ⁽⁴⁾	-4	4	kV

5 OPERATING CONDITIONS

Operating conditions are conditions under which the device is intended to be functional. All values are referenced to GND. MIN and MAX limits are valid for the recommended ambient temperature range of -40°C to 85°C.

Table 5: Operating conditions.

SYMBOL	PARAMETER	MIN ⁽¹⁾	TYP ⁽³⁾	MAX ⁽¹⁾	UNIT
V _{IN}	Input Voltage	2.5	ı	5.5	V
V _{OUT}	Output Voltage	0.8	ı	5.5	V
T _A	Ambient temperature range ⁽²⁾	-40	ı	85	°C
T _{jop}	Junction temperature range	-40	-	125	°C
l _{out}	Nominal output current ⁽⁵⁾	-	-	1	А

6 THERMAL SPECIFICATIONS

Table 6: Thermal specifications.

SYMBOL	PARAMETER	TYP ⁽³⁾	UNIT
Θ_{JA}	Junction-to-ambient thermal resistance ⁽²⁾	110	K/W
Ten	Thermal shutdown, rising	160	°C
I _{SD}	Thermal shutdown, hysteresis	10	°C

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7 ELECTRICAL SPECIFICATIONS

Caution:

MIN and MAX limits are valid for the recommended ambient temperature range of -40°C to 85°C. Typical values represents statistically the utmost probable values at the following conditions: V_{IN} = 5V, V_{OUT} = 1.8V, C_{IN} = 4.7 μ F ceramic, C_{OUT} = 10 μ F ceramic, $T_A = 25$ °C unless otherwise noted.

Table 7: Electrical specifications part 1.

SYMBOL	PARAMETER	TEST CONDITIONS	MIN ⁽¹⁾	TYP ⁽³⁾	MAX ⁽¹⁾	UNIT			
Output Current									
I _{OCP}	Overcurrent limit		1.5	2.3	3.0	А			
Output Voltage									
V_{FB}	Reference voltage		0.784	0.8	0.816	V			
I _{FB}	Feedback pin bias current		-50	_	50	nA			
	Line regulation	V _{IN} = V _{OUT} +1V to 5.5V, MODE = low	_	0.05	_	%			
	Load regulation	$500 \text{mA} \leq I_{LOAD} \leq 1 \text{A}$	_	0.9	_	%			
V_{OUT}	Output voltage ripple	V_{IN} = 3.6V, I_{OUT} = 100mA, MODE = high, 20MHz BWL ⁽⁶⁾	_	6	_	mV_{pp}			
	Output voltage ripple	$V_{IN} = 3.6V$, $I_{OUT} = 100$ mA, 20 MHz BWL $^{(6)}$		65	_	mV_{pp}			
		Switching Frequency							
f_{SW}	Switching frequency	MODE = high	3.6	4	4.4	MHz			
	E	nable and Undervoltage Lockout			-				
V _{UVLO}	V _{IN} undervoltage threshold	V _{IN} decreasing	2 2.1	2.1	2.2	V			
• UVLO	V _{IN} undervoitage unesnoid	V _{IN} undervoltage hysteresis		170	_	mV			
V_{EN}	EN threshold	Enable logic high		0.85	_	V			
o EM	Liverilesiloid	Enable logic low		0.75	_	V			
I _{EN}	EN pin input current	ENABLE = high	_	0.1	_	μΑ			
'EN	Liv piir input current	ENABLE = low		0.1	_	μΑ			
	Inpu	it Quiescent and Shutdown Current							
I_{SD}	Shutdown current	$V_{EN} = Iow, V_{IN} = 5V$	_	0.1	_	μΑ			
		MODE = high, switching with no load	_	12.8	_	mA			
I _{IN}	No load input current	MODE = low, switching with no load	_	27	_	μA			
1-	Quiescent current	MODE = high, no switching	1 —	23.5	_	μΑ			
Ι _Q	Quiescent current	MODE = low, no switching		22.5		μA			
		Soft-Start							
t _{SS}	Soft-start time	Rising edge to 95% of V _{OUT}	_	128	_	μs			
			-	•					

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ELECTRICAL SPECIFICATIONS

Caution:

MIN and MAX limits are valid for the recommended ambient temperature range of -40°C to 85°C. Typical values represents statistically the utmost probable values at the following conditions: V_{IN} =5V, V_{OUT} = 1.8V, C_{IN} = 4.7 μ F ceramic, C_{OUT} = 10 μ F ceramic, $T_A = 25$ °C unless otherwise noted.

Table 8: Electrical specifications part 2.

SYMBOL	PARAMETER	TEST CONDITIONS	MIN ⁽¹⁾	TYP ⁽³⁾	MAX ⁽¹⁾	UNIT			
	Efficiency								
		$V_{OUT} = 3.3V, I_{OUT} = 450mA$	_	92	_	%			
η	Efficiency	$V_{IN} = 3.6V, V_{OUT} = 3.3V,$ $I_{OUT} = 200mA$	_	96	_	%			
		$V_{IN} = 3.3V, V_{OUT} = 2.5V,$ $I_{OUT} = 300mA$	_	94	_	%			
	•	Mode Selection							
V_{MODE}	MODE threshold	MODE logic high	_	0.85	_	V			
MODE	WODE tillesiloid	MODE logic low	_	0.75	_	V			
1	MODE current	MODE logic high	_	75	_	nΑ			
I _{MODE}	consumption	MODE logic low	_	-60		nA			
Output Capacitance									
C _{OUT_MAX}	Maximum output capacitance		_	220	_	μF			

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RoHS, REACH

Table 9: RoHS, REACH.

RoHS directive

REACH directive



Directive 2011/65/EU of the European Parliament and the Council of June 8th, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

Directive 1907/2006/EU of the European Parliament and the Council of June 1st, 2007 regarding the Registration, Evaluation, Authorization and Restriction of Chemicals (REACH).

PACKAGE SPECIFICATIONS

Table 10: Package specifications.

ITEM	PARAMETER	TYP ⁽³⁾	UNIT
Lead finish	Silver-Palladium	_	_
Weight	_	0.0416	g

10 NOTES

- (1) Min and Max limits are 100% production tested at 25°C. Limits over the operating temperature range are guaranteed through correlation using Statistical Quality Control (SQC) methods.
- (2) Measured without heatsink, natural convection (0-20LFM / 0-0.1m/s) on the 178010502 evaluation board, a 40 x 40mm two layer board, with 35µm (1 ounce) copper.
- (3) Typical numbers are valid at 25°C ambient temperature and represent statistically the utmost probable values assuming a Gaussian distribution.
- (4) The human body model is a 100pF capacitor discharged through a $1.5\Omega k$ resistor into each pin. Test method is per JESD-22-114.
- (5) Depending on ambient temperature; see THERMAL DERATING.

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TYPICAL PERFORMANCE CURVES

If not otherwise specified, the following conditions apply: V_{IN} = 5V, V_{OUT} = 3.3V, C_{IN} = 4.7 μ F X5R ceramic, C_{OUT} = 10 μ F X5R ceramic, $C_{FF} = 22pF$, $T_A = 25$ °C.

11.1 RADIATED EMISSIONS EN55032 (CISPR-32) CLASS B COMPLIANT

Measured with module on an Evaluation Board 178010502 in a Fully Anechoic Room (FAR) at 3m antenna distance.

11.1.1 TEST SETUP

Input wire length:

Radiated Emission: 160cm (80cm Horizontal + 80cm Vertical)

Output wire length:

- Short wire (with input filter): Load directly on evaluation board
- Long wire (with input filter): 1m

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11.1.2 RADIATED EMISSIONS (Without Input Filter)

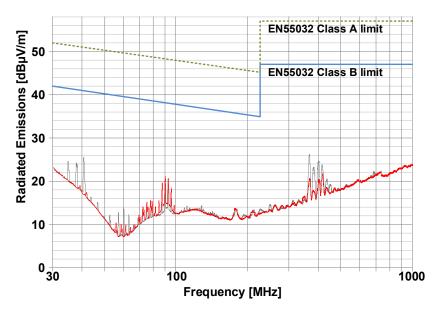


Figure 2: 171010502 radiated emissions (3m antenna distance) $I_{OUT} = 1A$ without input filter

11.1.3 RADIATED EMISSIONS (With Input Filter)

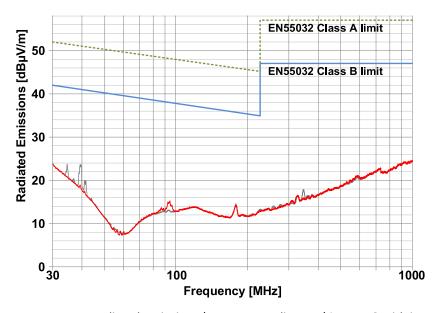


Figure 3: 171010502 radiated emissions (3m antenna distance) $I_{OUT} = 1A$ with input filter

The EMI behavior at the specified output current will be identical regardless of whether the MODE pin is pulled high or low.

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11.2 DC Performance Curves

11.2.1 Efficiency 5V_{IN} MODE = Low

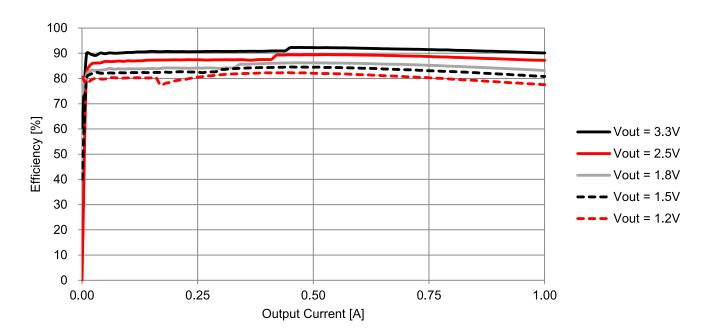


Figure 4: 171010502 efficiency V_{IN} = 5V, MODE = low.

11.2.2 Efficiency 3.6V_{IN} MODE = Low

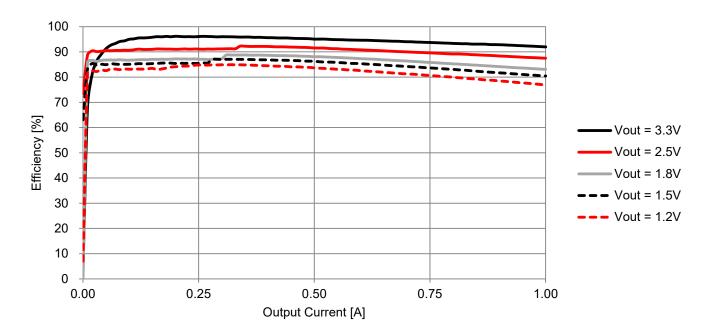


Figure 5: 171010502 efficiency V_{IN} = 3.6V, MODE = low.



11.2.3 Efficiency 3.3V_{IN} MODE = Low

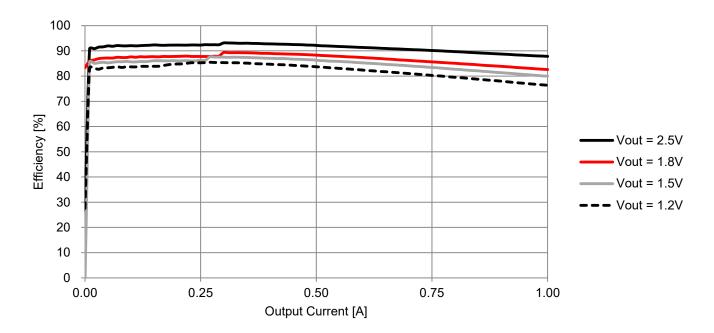


Figure 6: 171010502 efficiency V_{IN} = 3.3V, MODE = low.

11.2.4 Efficiency 5V_{IN} MODE = High

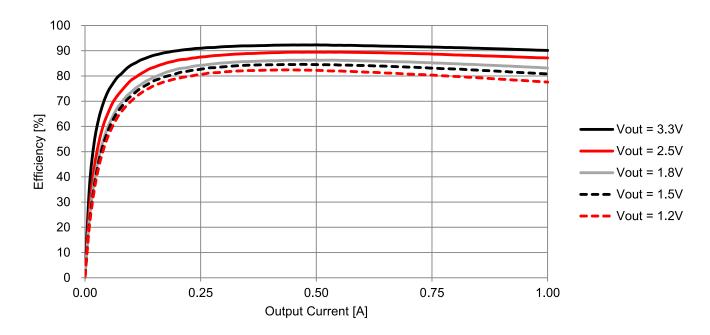


Figure 7: 171010502 output current thermal derating V_{IN} = 5V, MODE = high.



11.2.5 Efficiency 3.6V_{IN} MODE = High

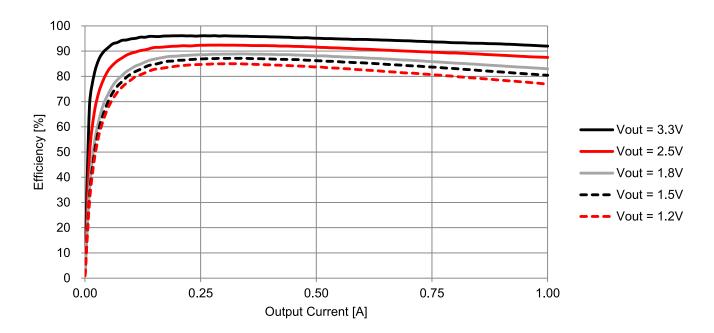


Figure 8: 171010502 output current thermal derating V_{IN} = 3.6V, MODE = high.

11.2.6 Efficiency 3.3V_{IN} MODE = High

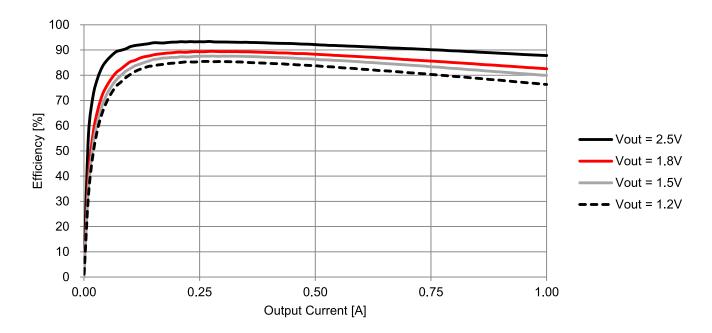


Figure 9: 171010502 load regulation V_{IN} = 3.3V, V_{OUT} = 1.8V, MODE = high.

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11.2.7 Thermal Derating 5VIN

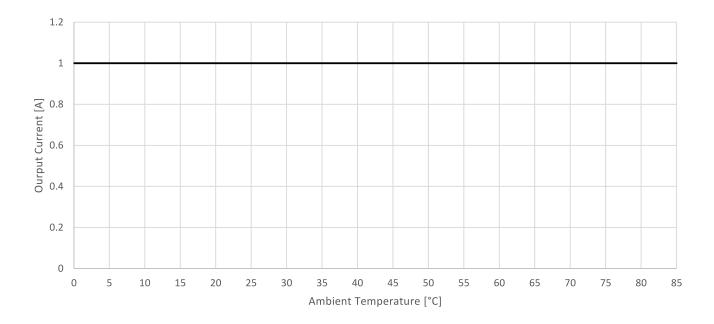


Figure 10: 171010502 output current thermal derating V_{IN} = 5V.

11.2.8 Thermal Derating 3.6VIN

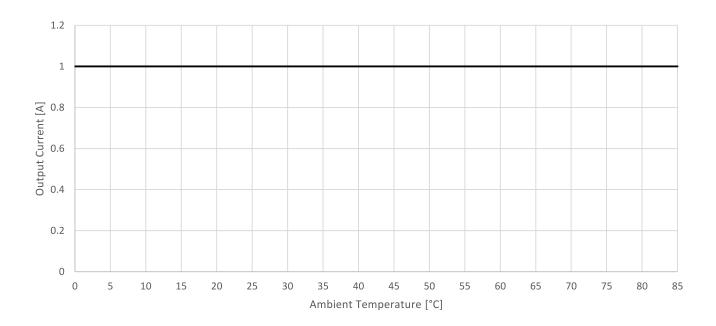


Figure 11: 171010502 output current thermal derating V_{IN} = 3.6V.

Note: Both thermal derating graphs were measured on the 178010502 Evaluation Board (40 x 40mm two layer board, with $35\mu m$ (1 ounce) copper). Please see T_A limits in OPERATING CONDITIONS.

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11.2.9 Load Regulation

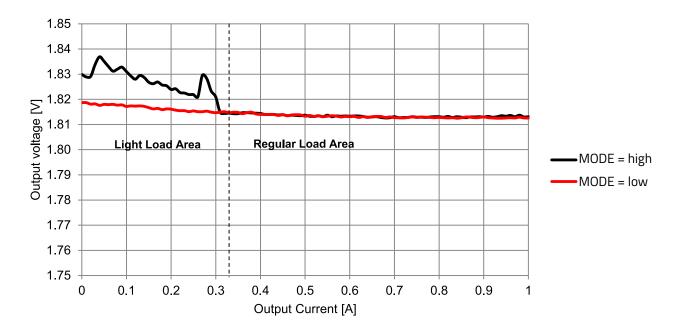


Figure 12: 171010502 load regulation $V_{IN} = 3.6V$, $V_{OUT} = 1.8V$.

11.2.10 Line Regulation

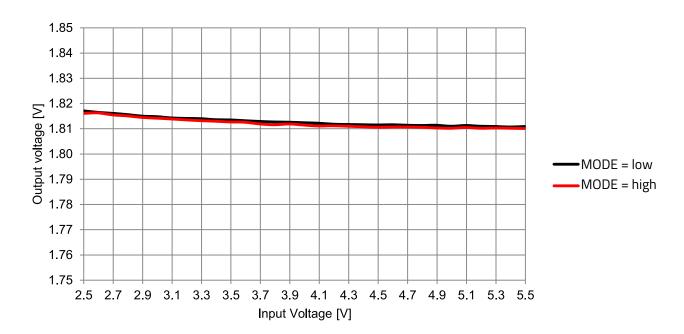


Figure 13: 171010502 line regulation $V_{OUT} = 1.8V$, $I_{OUT} = 1A$.

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BLOCK DIAGRAM 12

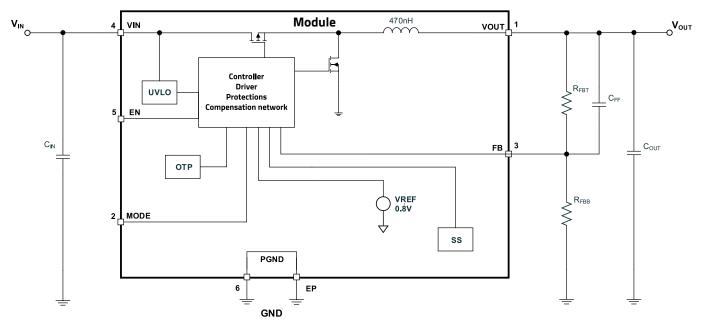


Figure 14: 171010502 block diagram.

CIRCUIT DESCRIPTION

The Magl³C power module 171010502 is a synchronous step down regulator with integrated MOSFETs, control circuitry and power inductor. The control scheme is based on a constant on-time (COT) regulation loop.

The V_{OUT} of the regulator is divided by the feedback resistor network R_{FBT} and R_{FBB} and fed into the FB pin. The internal comparator compares this signal with the internal 0.8V reference. If the feedback voltage is below the reference, the high side MOSFET is turned on for a fixed on-time.

The constant on-time control scheme does not require external compensation circuitry which makes the overall design very simple. Nevertheless, it requires a certain minimum ripple at the feedback pin. The Magl³C power module 171010502 generates this ripple internally and is supported by the C_{FF} capacitor which bypasses AC ripple directly to the feedback pin from the output. With this architecture very small output ripple values under 10mV_{PP} (similar to current or voltage mode devices) can be achieved.

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14 DESIGN FLOW

The following simple steps will show how to select the external components to design the 171010502 into an application.

Essential Steps

- 1. Set output voltage
- 2. Select input capacitor
- **3.** Select output capacitor
- 4. Select feed-forward capacitor

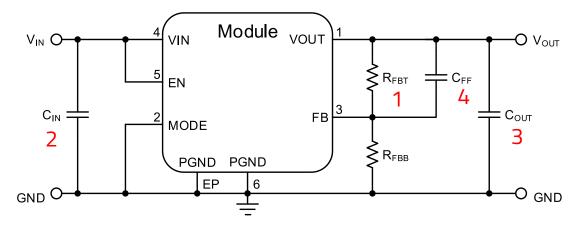


Figure 15: Design flow schematic.



STEP 1 Setting The Output Voltage (V_{OUT})

The output voltage is selected with an external resistor divider between V_{OUT} and GND (see circuit below). The voltage across the bottom resistor of the divider is provided to the FB pin and compared with an internal reference voltage of 0.8V (V_{REF}). The output voltage adjustment range is from 0.8V to 5.5V. The output voltage can be calculated according to the following formula:

$$V_{\rm OUT} = V_{\rm REF} \cdot (\frac{R_{\rm FBT}}{R_{\rm FBB}} + 1) \tag{1} \label{eq:vout}$$

One resistor must be chosen and then the other resistor can be calculated. For example, if R_{FBT} = 100k Ω then the resistance value of the lower resistor in the feedback network is indicated in the table below for common output voltages.

Table 11: Output voltage selection.

V _{OUT} (∨)	1.2	1.5	1.8	2.5	3.3	3.6	5
R_{FBB} (E96) (k Ω)	200	115	80.6	47.5	32.4	28.7	19.1

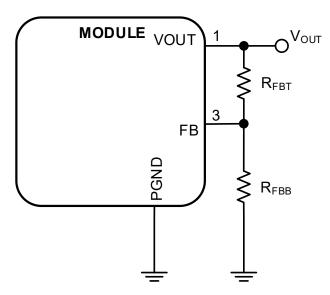


Figure 16: Output voltage schematic.

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14.2 STEP 2 Select The Input Capacitor (C_{IN})

An input capacitor of $4.7\mu\text{F}$ is integrated inside the 171010502 Magl³C power module, ensuring excellent EMI performance. An additional external input capacitance is required to provide the high input pulse current. The external input capacitor must be placed as close as possible to the VIN and PGND pins. For this Magl³C power module it is recommended to use an MLCC (multi-layer ceramic capacitor) of $4.7\mu\text{F}$. Attention must be paid to the voltage, frequency, and temperature deratings as well as the thermal class of the selected capacitor. The Würth Elektronik part number 885012207053 has been experimentally verified to work with this power module.

14.3 STEP 3 Select The Output Capacitor (C_{OUT})

The output capacitor should be selected in order to minimize the output voltage ripple and to provide a stable voltage at the output. It also affects the loop stability. An external MLCC of 10µF is recommended for all application conditions. Attention must be paid to the voltage, frequency, and temperature deratings as well as the thermal class of the selected capacitor. The Würth Elektronik part number 885012107014 has been experimentally verified to work with this power module.

In general, the output voltage ripple can be calculated using the following equation:

$$V_{\text{OUT ripple}} = \Delta I_{\text{L}} \cdot ESR + \Delta I_{\text{L}} \cdot (\frac{1}{8 \cdot f_{\text{SW}} \cdot C_{\text{OUT}}}) \tag{2}$$

where ΔI_L is the inductor current ripple and can be calculated with the following equation:

$$\Delta I_{\mathsf{L}} = \frac{V_{\mathsf{OUT}} \cdot (V_{\mathsf{IN}} - V_{\mathsf{OUT}})}{f_{\mathsf{SW}} \cdot L \cdot V_{\mathsf{IN}}} \tag{3}$$



STEP 4 Select The Feed-Forward Capacitor (C_{FF})

The 171010502 Magl³C power module allows for the selection of a feed forward capacitor, C_{FF}, providing a trade-off between response time and efficiency while also affecting the transition current threshold between COT and PFM operation. A lower value of C_{FF} will increase the light load conversion efficiency while slowing down the response time and increasing the overshoot and undershoot. Increasing the CFF value will decrease the response time and the overshoot and undershoot while decreasing light load conversion efficiency. Increasing the value of CFF results in higher value of current needed to leave PFM operation.

A CFF of 22pF has been evaluated experimentally as a value with suitable efficiency and transient characteristics for most applications. The Würth Elektronik part number 885012005009 has been experimentally verified to work with this power module.

The pictures below show the transient behavior of the 171010502 in response to a load transition from 0A to 1A using the recommended $C_{FF} = 22pF$, as well as other values of C_{FF} .

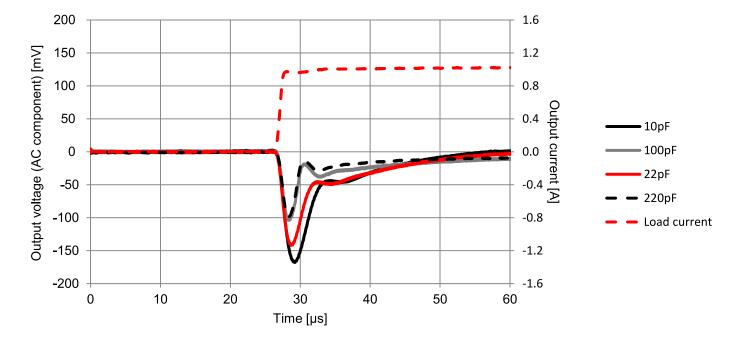


Figure 17: 171010502 load transient $V_{IN} = 5V$, $V_{OUT} = 3.3V$ from OA to 1A, MODE = high, $T_A = 25$ °C.

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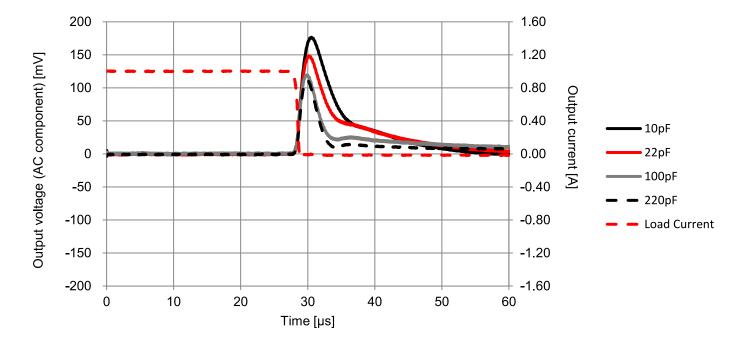


Figure 18: 171010502 load transient V_{IN} = 5V, V_{OUT} = 3.3V from 1A to 0A, MODE = high, T_A = 25°C.

These behaviors are valid only for the specified conditions and must be verified in the real application.

The C_{FF} value only affects the efficiency during light load conditions when the MODE pin is pulled low.

As explained in the section MODES OF OPERATION, during light load conditions with the MODE pin pulled low the device does not continuously switch, instead delivering energy to the load in bursts. The frequency between bursts is influenced by various parameters, including the C_{FF} value.

Increasing C_{FF} will cause the power module to burst more often, resulting in a decrease in light load efficiency.

While the recommended C_{FF} value of 22pF will work for most applications, the user can adjust the performance of the power module based on their application by trading between light load efficiency and transient response. This customization tailors the behavior of the power module to the application's needs. Any deviations from the recommended values and components should be thoroughly evaluated by the customer to ensure the device operates properly.



15 MODES OF OPERATION

The MODE pin of the 171010502 can be pulled either high or low to alter the light load performance of the power module based on the application requirements.

When pulled high, COT operation will be forced throughout the entire load current range. When pulled low, PFM operation will occur during light load conditions.

The power module will operate in one of four modes, depending on the operating conditions.

15.1 Constant On-Time (COT) Operation

The power module operates at a fixed switching frequency of 4MHz where the duty cycle (D) is determined by the following equation:

$$D = \frac{V_{\text{OUT}}}{V_{\text{IN}}} \tag{4}$$

The on-time is determined by the duty cycle and the switching frequency as follows:

$$t_{\rm ON} = \frac{D}{f_{\rm SW}} \tag{5}$$

The on and off-times can be related to the switching frequency as follows:

$$\frac{1}{f_{\text{SM}}} = t_{\text{ON}} + t_{\text{OFF}} \tag{6}$$

The mode of operation has a minimum off-time value of 60ns.

15.2 Fixed Off-Time Operation

When the minimum off-time of 60ns is reached and the duty cycle must increase futher, the power module fixes the off-time to 60ns and begins increasing the on-time. This results in a decrease in switching frequency proportional to the increase in duty cycle.

15.3 100% Duty Cycle Operation

When the input voltage approaches the output voltage and the duty cycle approaches 100%, the power module will leave the high side MOSFET on continuously and the output voltage will be limited by the input voltage. Further decreases of input voltage will result in a corresponding decrease in output voltage.

15.4 Pulse Frequency Modulation (PFM) Operation

If the MODE pin is pulled low PFM operation is initiated when the power module enters discontinuous mode. A burst of switching cycles increases the output voltage above the set value followed by a period of dead time where the output current is only delivered by the output capacitor. This results in slightly increased output voltage ripple in exchange for significantly increased conversion efficiency.

The frequency of the bursts depends on the load and is significantly lower than the default switching frequency. As the output current demand increase the bursts become more frequent until the module automatically transitions out of PFM operation.

The burst frequency is a function of input voltage, output voltage, output current, C_{FF} , and C_{OUT} . Changing any of these parameters will alter the device's behavior during PFM operation.

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OUTPUT VOLTAGE RIPPLE 16

The output voltage ripple is influenced by the condition applied to the MODE pin and the output current drawn from the module. If the MODE pin is pulled high and the duty cycle is below 76%, the ripple is very low and it always has the same frequency as the internal oscillator (4MHz typ.). If MODE is pulled low and either the load current is low enough or the duty cycle is high enough then the output voltage ripple will be higher and the frequency lower than the nominal switching frequency (see pictures below).

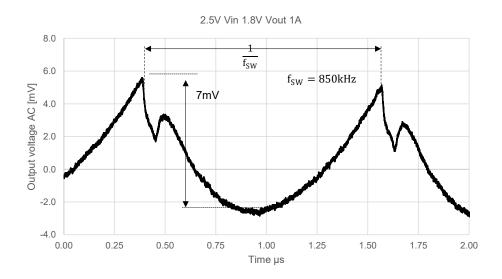


Figure 19: 171010502 output voltage ripple $V_{IN} = 3.6V$, VOUT = 1.8V, $I_{OUT} = 0.1A$, $C_{OUT} = 10\mu F$, MODE = low.

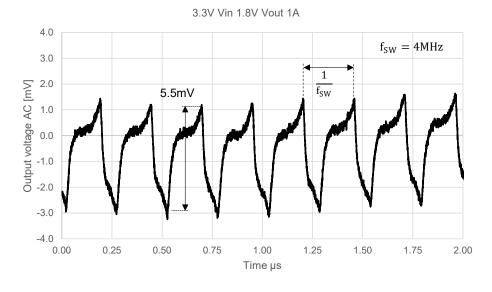


Figure 20: 171010502 output voltage ripple V_{IN} = 3.6V, VOUT = 1.8V, I_{OUT} = 0.1A, C_{OUT} = 10 μ F, MODE = high.

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17 PROTECTION FEATURES

17.1 Overcurrent Protection (OCP)

For protection against load faults, the 171010502 $MagI^3C$ power module incorporates a cycle-by-cycle current limit (see I_{OCP} in ELECTRICAL SPECIFICATIONS). During switching, the output current is limited by turning off the high-side switch when the current limit value is detected. This switching behavior continues, limiting the on-time of the device until the overcurrent condition is removed. When the overcurrent condition is removed, normal switching behavior resumes.

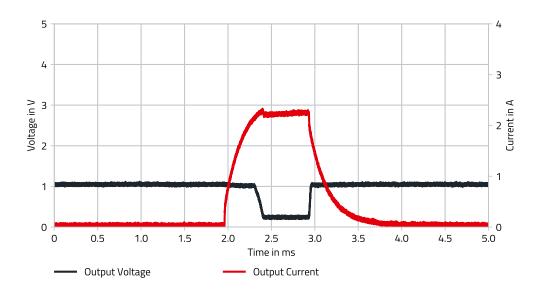


Figure 21: 171010502 overcurrent protection V_{IN} = 3.6V, V_{OUT} = 1.8V, I_{OUT} > 2A.

17.2 Short Circuit Protection (SCP)

When the 171010502 Magl³C power module experiences a short circuit condition at the output it will limit the current, typically to 2.2A, until the thermal protection circuit shuts the module off. If the short circuit condition is removed, normal switching operation will begin if the module temperature is not exceeding the thermal shutdown threshold.

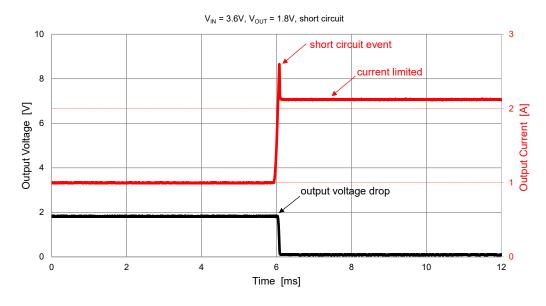


Figure 22: 171010502 short circuit protection $V_{IN} = 3.6V$, $V_{OUT} = 1.8V$, short circuit at output.



Over Temperature Protection (OTP)

Thermal protection helps prevent catastrophic failures due to accidental device overheating. The junction temperature of the 171010502 Magl³C power module should not be allowed to exceed its maximum ratings. Thermal protection is implemented by an internal thermal shutdown circuit, which activates when the junction temperature reaches 160°C (typ). Under the thermal shutdown condition both MOSFETs remain off causing V_{OUT} to drop. When the junction temperature falls below the hysteretic value, the internal soft-start is released, V_{OUT} rises smoothly, and normal operation resumes.

17.4 **Undervoltage Lockout (UVLO)**

The device incorporates input undervoltage lockout (UVLO) to protect from unexpected behavior at input voltages below the recommended values. The thresholds of the UVLO are indicated in the ELECTRICAL SPECIFICATIONS.

17.5 Soft-Start

The 171010502 Magl³C power module implements an internal soft-start in order to limit the inrush current and avoid output voltage overshoot during start-up.

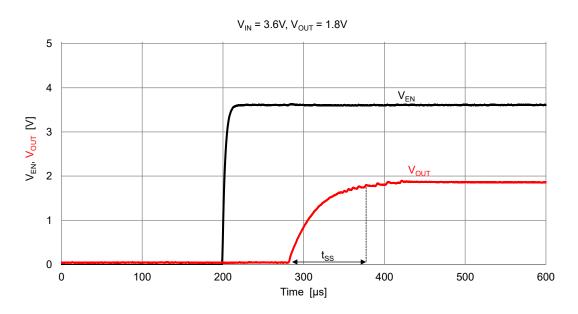


Figure 23: 171010502 soft-start $V_{IN} = 3.6V$, $V_{OUT} = 1.8V$.

17.6 Enable

The 171010502 Magl³C power module is enabled by setting the pin EN high. After setting EN high the module prepares for operation. Once prepared, the module begins switching and the internal soft-start regulates the output voltage rise until the desired output voltage is met allowing normal operation to take place.

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18 DESIGN EXAMPLE

18.1 Layout

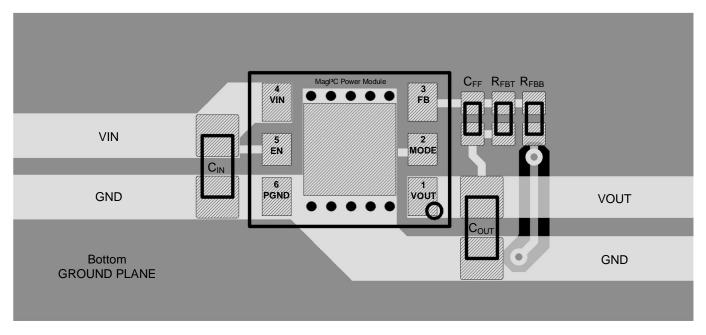


Figure 24: 171010502 layout recommendation.

The picture above shows a possible layout for the 171010502 Magl³C power module. Nevertheless, some recommendations should be followed when designing the layout:

- 1. The exposed pad should be connected to the bottom copper layer of the circuit board with sufficient vias to optimize the heat dissipation during operation. The above example uses 10 vias each with a drill diameter of 200µm. Ensure that nearby vias are either plugged or covered in solder mask to ensure the best solderability.
- 2. The input and output capacitors should be placed as close as possible to the VIN, VOUT and PGND pins of the device.
- 3. The feedback resistor divider should be placed as close as possible to the VOUT and FB pins.
- 4. Pins 5 and 2 (EN and MODE respectively) must always be connected to either VIN or PGND and cannot be left floating (an example is shown in the layout depicted above, where EN and MODE Pins are connected to VIN and PGND respectively).



18.2 Schematic

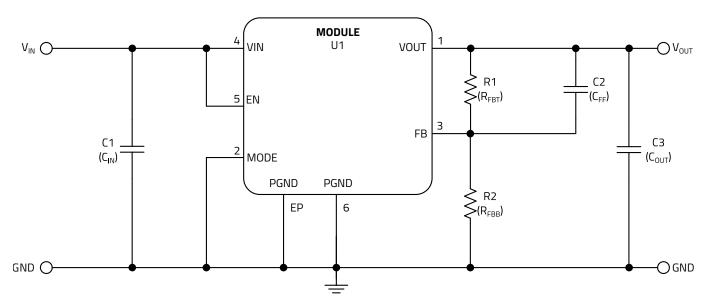


Figure 25: 171010502 design example schematic.

18.3 Bill of Materials

Table 12: 171010502 bill of materials.

Designator	Description	Quantity	Order Code	Manufacturer
U1	Magl ³ C power module	1	171010502	WE
C1, C3	Ceramic chip capacitor 10µF/16V X5R, 0805	2	885012107014	WE
C2	Ceramic chip capacitor 22pF/25V NP0, 0603	1	885012005009	WE
R1	100kΩ	1		
R2	49.9k Ω for V _{OUT} = 1.8V	1		



19 HANDLING RECOMMENDATIONS

- 1. The power module is classified as MSL1 (JEDEC Moisture Sensitivity Level 1) according to JEDEC J-STD033.
- 2. The components should be sealed and stored in a controlled environment prior to soldering or other use.
- 3. If the components are to be baked prior to soldering, the baking must be performed with the components in an inert gas such as nitrogen or argon.
- 4. Maximum numbers of reflow cycles is two.
- 5. For minimum risk, solder the module in the last reflow cycle of the PCB production.
- 6. Please consider that the leads are finished with AgPd.
- 7. For solder paste use a standard SAC Alloy such as SAC 305, type 3 or higher.
- 8. The profile below is valid for convection reflow only.
- 9. Other soldering methods (e.g. vapor phase) are not verified and have to be validated by the customer at their own risk

20 SOLDERING PROFILE

Table 13: Reflow soldering profile.

Profile Feature	Symbol	Value
Preheat temperature minimum	T _{s_min}	150°C
Preheat temperature maximum	T _{s_max}	180°C
Preheat time from T_{s_min} to T_{s_max}	t _s	60-90 seconds
Liquidous temperature	T _L	217°C
Time maintained above T _L	t∟	60-90 seconds
Classification temperature	T _C	240°C
Peak package body temperature	T _P	$T_P \leq T_C$
Time within T _C - 5°C and T _C	t _P	$t_P \leq 20 \ seconds$
Ramp-up Rate $(T_L \text{ to } T_p)$		3°C/second maximum
Ramp-down rate $(T_p \text{ to } T_L)$		3°C/second maximum
Time 25°C to peak temperature		8 minutes maximum

Please refer to JEDEC J-STD020E for further information pertaining to reflow soldering of electronic components.

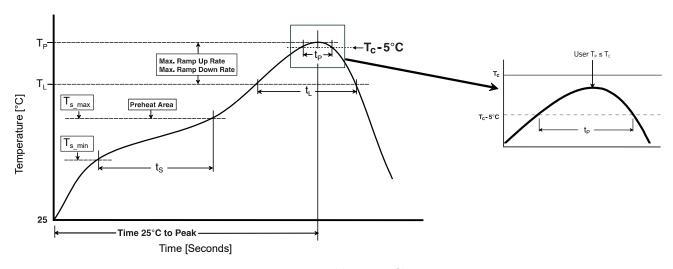


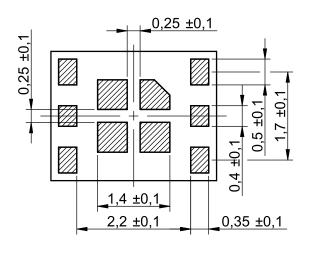
Figure 26: Soldering profile.

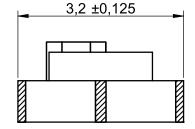
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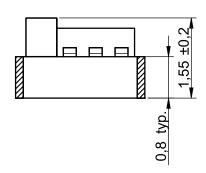


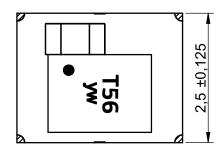
PHYSICAL DIMENSIONS 21

21.1 Component









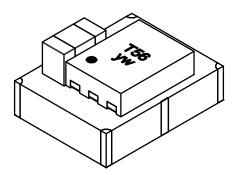


Figure 27: 171010502 module dimensions.

All dimensions in mm Tolerances $\pm 0,1$ mm unless otherwise specified

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21.2 Example Landpattern

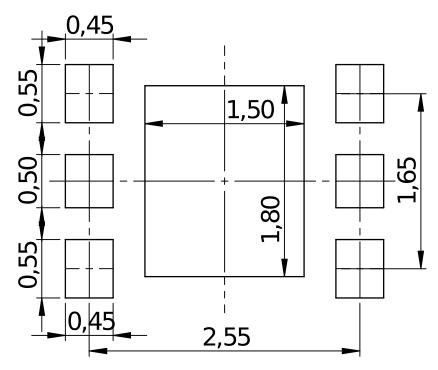


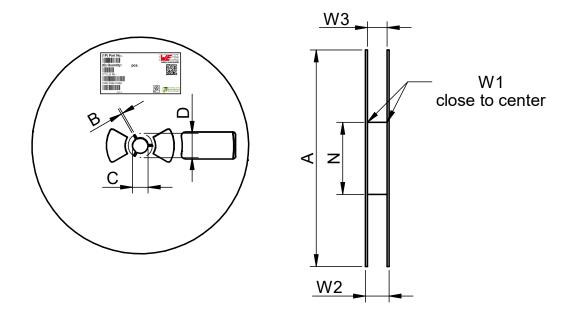
Figure 28: 171010502 example landpattern.

All dimensions in mm Stencil thickness of 100µm



21.3 Packaging

Reel in mm



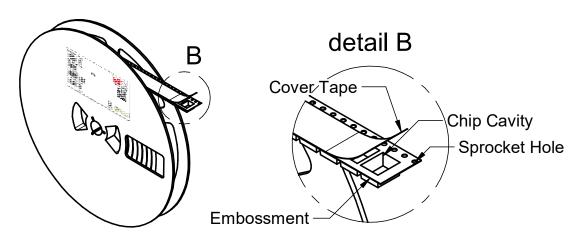


Figure 29: 171010502 reel dimensions.

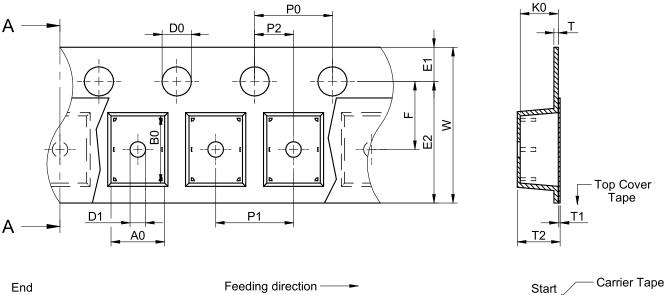
Table 14: Reel dimensions.

Α	В	С	D	N	W1	W2	W3	Material
Тур.	Min.	±0.8	Min.	Min.	±1.5	Max.	Min.	
178.00	1.5	13.00	20.20	50.00	8.40	14.40	7.90	Polystyrene

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Tape in mm



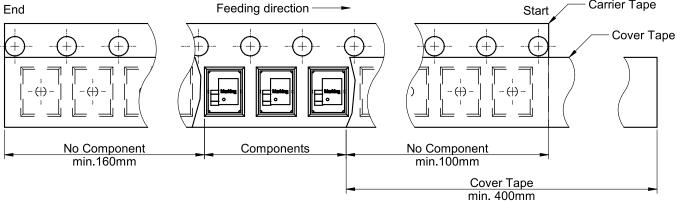


Figure 30: 171010502 tape dimensions.

AO	во	w	Т	T1	T2	DO	E1	E2	F	PO	P1	P2	Packaging Unit
±0.1	±0.1	±0.1	±0.1	±0.05	Max.	Тур.	±0.1	±0.1	Min.	±0.1	±0.1	±0.05	
2.75	3.45	8.00	4.00	0.22	0.10	2.20	1.50	1.75	6.25	3.50	4.00	2.00	2000

Tape material is polystyrene.

Magl³C Power Module

WPME-VDMM - Variable Step Down MicroModule





22 DOCUMENT HISTORY

Table 15: Document history.

Revision	Date	Description	Comment
1.0	January 2019	Initial data sheet release.	
2.0	January 2020	PCN	Updated format, circuit descriptions and electrical specifications
			Würth Elektronik has added the maximum allowable output capacitance that can be used at the output of the power module. Würth Elektronik has updated:
			 The minimum and maximum storage temperature (page 4).
			 The junction to ambient thermal resistance (page 4).
			 The pin ESD voltage ratings (page 4).
			 The layout recommendation to improve readability and recommended practices (page 26).
3.0	August 2021	PCN	 The solder handling instructions (no change to actual profile) (page 28).
			 The evaluation board bill of material to reflect the evaluation board (page 27).
			 The cautions and warnings of the data sheet (page 34).
			 The package and packaging drawings (page 29).
			 The format of the data sheet to improve readability of the document.
3.1	June 2022	Minor change.	Corrected pinout drawing by moving exposed pad notch (page 2).
			Würth Elektronik has updated or corrected:
			 Line and load regulation units.
			Input current values.
			Modes of operation.
			Overcurrent graph.
			 Handling recommendations.
4.0	September 2024	PCN	■ MSL level.
			 Number of allowed solder cycles.
			 Component storage and baking instructions.
			■ Block diagram.
			 Absolute maximum voltage values.
			 Resistor value for 5V in design flow.
tasheet Ve	rsion / O		© September 20

Magl³C Power Module

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Magl³C Power Module

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25 CAUTIONS AND WARNINGS

The following conditions apply to all goods within the product series of MagI³C of Würth Elektronik eiSos GmbH & Co. KG:

General:

- All recommendations according to the general technical specifications of the data-sheet have to be complied with.
- The usage and operation of the product within ambient conditions which probably alloy or harm the component surface has to be avoided.
- The responsibility for the applicability of customer specific products and use in a particular customer design is always within the authority of the customer. All technical specifications for standard products do also apply for customer specific products
- Residual washing varnish agent that is used during the production to clean the application might change the characteristics of the body, pins or termination. The washing varnish agent could have a negative effect on the long term function of the product. Direct mechanical impact to the product shall be prevented as the material of the body, pins or termination could flake or in the worst case it could break. As these devices are sensitive to electrostatic discharge customer shall follow proper IC Handling Procedures.
- Customer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of Würth Elektronik eiSos GmbH & Co. KG components in its applications, notwithstanding any applications-related information or support that may be provided by Würth Elektronik eiSos GmbH & Co. KG.
- Customer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences lessen the likelihood of failures that might cause harm and take appropriate remedial actions
- Customer will fully indemnify Würth Elektronik eiSos and its representatives against any damages arising out of the use of any Würth Elektronik eiSos GmbH & Co. KG components in safety-critical applications

Product specific:

Follow all instructions mentioned in the datasheet, especially:

- The solder profile has to comply with the technical reflow or wave soldering specification, otherwise this will void the warranty.
- All products are supposed to be used before the end of the period of 12 months based on the product date-code.
- Violation of the technical product specifications such as exceeding the absolute maximum ratings will void the warranty.
- It is also recommended to return the body to the original moisture proof bag and reseal the moisture proof bag again.
- ESD prevention methods need to be followed for manual handling and processing by machinery.

Disclaimer:

This electronic component has been designed and developed for usage in general electronic equipment only. This product is not authorized for use in equipment where a higher safety standard and reliability standard is especially required or where a failure of the product is reasonably expected to cause severe personal injury or death, unless the parties have executed an agreement specifically governing such use. Moreover Würth Elektronik eiSos GmbH & Co. KG products are neither designed nor intended for use in areas such as military, aerospace, aviation, nuclear control, submarine, transportation (automotive control, train control, ship control), transportation signal, disaster prevention, medical, public information network etc. Würth Elektronik eiSos GmbH & Co. KG must be informed about the intent of such usage before the design-in stage. In addition, sufficient reliability evaluation checks for safety must be performed on every electronic component which is used in electrical circuits that require high safety and reliability functions or performance. These cautions and warnings comply with the state of the scientific and technical knowledge and are believed to be accurate and reliable. However, no responsibility is assumed for inaccuracies or incompleteness.

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26 IMPORTANT NOTES

General Customer Responsibility

Some goods within the product range of Würth Elektronik eiSos GmbH & Co. KG contain statements regarding general suitability for certain application areas. These statements about suitability are based on our knowledge and experience of typical requirements concerning the areas, serve as general guidance and cannot be estimated as binding statements about the suitability for a customer application. The responsibility for the applicability and use in a particular customer design is always solely within the authority of the customer. Due to this fact it is up to the customer to evaluate, where appropriate to investigate and decide whether the device with the specific product characteristics described in the product specification is valid and suitable for the respective customer application or not. Accordingly, the customer is cautioned to verify that the datasheet is current before placing orders.

Customer Responsibility Related to Specific, in Particular Safety-Relevant, Applications

It has to be clearly pointed out that the possibility of a malfunction of electronic components or failure before the end of the usual lifetime cannot be completely eliminated in the current state of the art, even if the products are operated within the range of the specifications. In certain customer applications requiring a very high level of safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health it must be ensured by most advanced technological aid of suitable design of the customer application that no injury or damage is caused to third parties in the event of malfunction or failure of an electronic component.

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Due to constant product improvement product specifications may change from time to time. As a standard reporting procedure of the Product Change Notification (PCN) according to the JEDEC-Standard we inform about minor and major changes. In case of further queries regarding the PCN, the field sales engineer or the internal sales person in charge should be contacted. The basic responsibility of the customer as per Section 1 and 2 remains unaffected.

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Due to technical progress and economical evaluation we also reserve the right to discontinue production and delivery of products. As a standard reporting procedure of the Product Termination Notification (PTN) according to the JEDEC Standard we will inform at an early stage about inevitable product discontinuance. According to this we cannot guarantee that all products within our product range will always be available. Therefore it needs to be verified with the field sales engineer or the internal sales person in charge about the current product availability expectancy before or when the product for application design-in disposal is considered. The approach named above does not apply in the case of individual agreements deviating from the foregoing for customer-specific products.

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